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2018 IEEE 68th Electronic Components and Technology Conference ECTC 2018

Table of Contents

Welcome Message from the General Chair and Program Chair	lv
Executive Committee	lvii
Program Committee	lviii

Session 1: Flexible Electronics, Substrate for High Frequency Applications

 In-Situ Stress Determination of Electroless Cu on PCB-Relevant Substrates
 Stretchable, Printable and Electrically Conductive Composites for Wearable RF Antennas
 A Study on the Anchoring Polymer Layer(APL) Solder Anisotropic Conductive Films (ACFs) for Ultra Fine Pitch Flex-on-Flex (FOF) Assembly Using an Ultrasonic Bonding Method
Development of Novel BT Laminate Material for Low-Loss and High Speed Transmission

Organic Substrate Material with Low Transmission Loss and Effective in Suppressing Package Warpage
for 5G Application
Shunsuke Tonouchi (Hitachi Chemical Co. Ltd.), Etsuo Mizushima
(Hitachi Chemical Co. Ltd.), Tomio Fukuda (Hitachi Chemical Co. Ltd.),
Tomokazu Shimada (Hitachi Chemical Co. Ltd.), Yukio Nakamura (Hitachi
Chemical Co. Ltd.), and Toshiyuki Iijima (Hitachi Chemical Co. Ltd.)
 Porous Epoxy Film for Low Dielectric Constant Chip Substrates and Boards
Development of Multi-layered Build-Up Insulation Dry-Film Material for Ultra-Low Transmission Loss Wirings for High-Speed Semi-Conductor Packaging

Session 2: Advances in Wafer and Panel Level Fan-Out Packaging

A Novel Submicron Polymer Re-Distribution Layer Technology for Advanced InFO Packaging Han-Ping Pu (Taiwan Semiconductor Manufacturing Company Ltd.), H. J. Kuo (Taiwan Semiconductor Manufacturing Company Ltd.), C. S. Liu (Taiwan Semiconductor Manufacturing Company Ltd.), and Douglas C. H. Yu (Taiwan Semiconductor Manufacturing Company Ltd.)	45
 Fan-Out Panel Level Package with Fine Pitch Pattern	52
Ultra Fine RDL Structure Fabrication Using Alternative Patterning and Bottom-Up Plating Processes Richard Hollman (TEL Advanced Packaging), Ognian Dimov (Fujifilm Electronic Materials), Sanjay Malik (Fujifilm Electronic Materials), Habib Hichri (SUSS Microtec Photonic Systems Inc), and Markus Arendt (SUSS Microtec Photonic Systems Inc)	58
Low Cost Si-Less RDL Interposer Package for High Performance Computing Applications	54

Panel Level Packaging - A View Along the Process Chain	70
Tanja Braun (Fraunhofer IZM), KF. Becker (Fraunhofer IZM), O. Hoelck	
(Fraunhofer IZM), R. Kahle (Fraunhofer IZM), M. Wöhrmann (Fraunhofer	
IZM), L. Boettcher (Fraunhofer IZM), M. Töpper (Fraunhofer IZM), L.	
Stobbe (Fraunhofer IZM), H. Zedel (Fraunhofer IZM), R. Aschenbrenner	
(Fraunhofer IZM), S. Voges (Technical University Berlin), M.	
Schneider-Ramelow (Technical University Berlin), and KD. Lang	
(Technical University Berlin)	
Patterning High Resolution Features Through the Integration of an Advanced Lithography System with a	
Novel Nozzleless Spray Coating Technology	79
Jack Mach (Rudolph Technologies), Corey Shay (Rudolph Technologies),	
Stuart Erickson (Ultrasonic Systems Inc.), and Gary Smith (Sumitomo	
Chemical Advanced Technologies)	
Extreme Thinned-Wafer Bonding Using Low Temperature Curable Polyimide for Advanced Wafer Level	
Integrations	86
Julien Bertheau (Imec), Fumihiro Inoue (Imec), Alain Phommahaxay	
(Imec), lan Peng (Imec), Serena Iacovo (Imec), Nouredine Rassoul	
(Imec), Erik Sleeckx (Imec), Kenneth Rebibs (Imec), Andy Miller	
(Imec), Gerald Beyer (Imec), Eric Beyne (Imec), and Atsushi Nakamura	
(Fujifilm)	

Session 3: 3D Design, Assembly and Additive Manufacturing

Novel Failure Analysis Techniques for 1.8 µm Pitch Wafer-to-Wafer Bonding Christian Schmidt (ZEISS), Lorenz Lechner (ZEISS), Ingrid De Wolf (IMEC and also KU Leuven), Soon-Wook Kim (IMEC), and Eric Beyne (IMEC)	92
Column Interconnects: A Path Forward for Embedded Cooling of High Power 3D Chip Stacks Mark Schultz (IBM TJ Watson Research), Cyril Cabral Jr. (IBM TJ Watson Research), Cornelia Tsang (Raytheon), Joana Maria (IBM TJ Watson Research Center), Paul Andry (IBM TJ Watson Research), Qianwen Chen (IBM TJ Watson Research), and Timothy Chainer (IBM TJ Watson Research)	97
Assembly Process Development of Ultra Large Scale 3D Stacking with Transmission Circuits Via TSVs Shunichi Kikuchi (Fujitsu Limited), Hidehiko Kira (Fujitsu Limited), Makoto Suwada (Fujitsu Limited), Tatsumi Nakada (Fujitsu Limited), Naoaki Nakamura (Fujitsu Advanced Technologies Limited), Norio Kainuma (Fujitsu Advanced Technologies Limited), Kazuhiro Kanai (Fujitsu Advanced Technologies Limited), and Takumi Masuyama (Fujitsu Advanced Technologies Limited)	103
The Principles of "Smart" Encapsulation: Using Additive Printing Technology for the Realization of Intelligent Application-Specific Packages for IoT, 5G, and Automotive Radar Applications Bijan Tehrani (Georgia Institute of Technology), Ryan Bahr (Georgia Institute of Technology), Daniel Revier (Texas Instruments), Benjamin Cook (Texas Instruments), and Manos Tentzeris (Georgia Institute of Technology)	111
A New Microsystem Packaging Approach Using 3D Printing Encapsulation Process Baptiste Goubault (CEA-LETI), Gabrielle Aspar (CEA-LETI), Jean-Charles Souriau (CEA-LETI), Laetitia Castagne (CEA-LETI), SimonGilles Simon (CEA-LETI), Lea Di Cioccio (CEA-LETI), and Yves Bréchet (CEA)	118

A Design Study of 3D Printed Reduced Height Waveguide Structures	125
Vincens Gjokaj (Michigan State University) and Premjeet Chahal	
(Michigan State University)	
Self-Powered, Inkjet Printed Electrochromic Films on Flexible and Stretchable Substrate for Wearable	
Electronics Applications	131
Ebraheem Ali Azhar (Arizona State University), Terry Alford (Arizona	
State University), and Hongbin Yu (Arizona State University)	

Session 4: Automotive and Harsh Environment Reliability

Novel Corrosion Prevention Treatments for Cu Wire Bonded Device to Improve Bonding Reliability Muthappan Asokan (University of North Texas), Josh Caperton (University of North Texas), Zach Thompson (University of North Texas), Oliver Chyan (University of North Texas), Mahmud Chowdhury (Texas Instruments Inc.), Shawn O'Connor (Texas Instruments Inc.), and Luu Nguyen (Texas Instruments Inc.)	. 139
A Monte Carlo Approach to Predicting Failure Across Multiple Temperature and Humidity Field Environments Jonathon Tucker (Microsoft Corporation), Ramji Dhakal (Microsoft Corporation), George Thiel (Microsoft Corporation), and Virendra Jadhav (Microsoft Corporation)	. 144
Improve Interconnect Reliability of BGA Substrate with Stacked Vias by Reducing Carbon Inclusion in the Interface Between Via and Land Pad	. 150
Understanding Underfill Degradation in Reliability Testing Conditions for ADAS Package Development Ziyin Lin (Intel), Vijay Subramanian (Intel), Pramod Malatkar (Intel), and Nisha Ananthakrishnan (Intel)	. 157
Quantification and Modeling of Microstructural Evolution in Lead Free Solders During Long Term Isothermal Aging	. 162
Reliability Enhancement of Automotive Electronic Modules Using Various Glues Dongji Xie (Nvidia Corp.), Zhongming Wu (Nvidia Corp.), Joe Hai (Nvidia Corp.), and Manthos Economou (Nvidia Corp.)	. 172
 High-Temperature And Moisture-Ageing Reliability of High-Density Power Packages For Electric Vehicles Shreya Dwarakanath (Georgia Institute of Technology), P. Markondeya Raj (Georgia Institute of Technology), Vanessa Smet (Georgia Institute of Technology), Venky Sundaram (Georgia Institute of Technology), Mark D Losego (Georgia Institute of Technology), and Rao Tummala (Georgia Institute of Technology) 	. 179

Session 5: Antenna-in-Package for RF and mm-Wave Systems

Small Shielded Bluetooth Module Equipped with Slot Antenna on the Surface	185
A 77GHz Antenna-in-Package with Low-Cost Solution for Automotive Radar Applications Cheng-Yu Ho (Advanced Semiconductor Engineering Inc.), Sheng-Chi Hsieh (Advanced Semiconductor Engineering Inc.), Ming-Fong Jhong (Advanced Semiconductor Engineering Inc.), Chen-Chao Wang (Advanced Semiconductor Engineering Inc.), and and Chun-Yen Ting (Advanced Semiconductor Engineering Inc.)	191
An Enhanced 64-Element Dual-Polarization Antenna Array Package for W-Band Communication and Imaging Applications	197
Xiaoxiong Gu (IBM T. J. Watson Research Center), Duixian Liu (IBM T. J. Watson Research Center), Chris Baks (IBM T. J. Watson Research Center), Jean-Olivier Plouchart (IBM T. J. Watson Research Center), Wooram Lee (IBM T. J. Watson Research Center), and Alberto Valdes-Garcia (IBM T. J. Watson Research Center)	
 InFO_AiP Technology for High Performance and Compact 5G Millimeter Wave System Integration	202
Mm-Wave Antenna in Package (AiP) Design Applied to 5th Generation (5G) Cellular User Equipment Using Unbalanced Substrate	208
Ying-Wei Lu (Siliconware Precision Industries Co. Ltd.), Bo-Siang Fang (Siliconware Precision Industries Co. Ltd.), Hsuan-Hao Mi (Siliconware Precision Industries Co. Ltd.), and Kuan-Ta Chen (Siliconware Precision Industries Co. Ltd.)	
Novel 3D-/Inkjet-Printed Flexible On-package Antennas, Packaging Structures, and Modules for Broadband 5G Applications	214

Session 6: Warpage and Moisture Characterization

A Novel Finite Element Technique for Moisture Diffusion Modeling Using ANSYS Cagan Diyaroglu (University of Arizona), Selda Oterkus (University of Strathclyde), and Erkan Oterkus (University of Strathclyde)	227
Adaptive Curvature Flexure Test to Assess Flexible Electronic Systems Rui Chen (Georgia Institute of Technology), Justin Chow (Georgia Institute of Technology), Christine Taylor (Georgia Institute of Technology), Jeffrey Meth (DuPont Electronics & Imaging), and Suresh Sitaraman (Georgia Institute of Technology)	236
Parametric Optimization and Yield Probability Prediction of Package Warpage Shenghua Huang (Western Digital), Zhongli Ji (Western Digital), Yangming Liu (Western Digital), Ning Ye (Western Digital), and Hem Takiar (Western Digital)	243
An Integrated Warpage Prediction Model Based on Chemical Shrinkage and Viscoelasticity for Molded Underfill Shu-Shen Yeh (TSMC), Po-Yao Lin (TSMC), Kuang-Chun Lee (TSMC), Jin-Hua Wang (TSMC), Wen-Yi Lin (TSMC), Ming-Chih Yew (TSMC), Po-Chen Lai (TSMC), Chia-Kuei Hsu (TSMC), Che-Chia Yang (TSMC), and Shin-Puu Jeng (TSMC)	249
Trend Plots for Different Mold-Thick Selection on Warpage Design of MUF FCCSP with 4L ETS Chih-Sung Chen (Siliconware Precision Industries Co. Ltd.), Nicholas Kao (Siliconware Precision Industries Co. Ltd.), and Don Son Jiang (Siliconware Precision Industries Co. Ltd.)	255
Numerical/Experimental Hybrid Approach to Predict Warpage of Thin Advanced Substrates Byung Kim (University of Maryland) and Bongtae Han (University of Maryland)	267
 Warpage and Thermal Stress under Thermal Cycling Test in SiC and Si Power Device Structures Using Direct Chip-Bonding with Ag Sintered Layer on Cu Plate	273

Session 7: Low Temperature Metallic Interconnection Technologies

Laser Sintering of Dip-Based All-Copper Interconnects	279
Low Temperature Fine-Pitch Wafer-Level Cu-Cu Bonding Using Nanoparticles Fabricated by PVD2 Zijian Wu (Tsinghua University), Qian Wang (Tsinghua University), Changming Song (Tsinghua University), and Jian Cai (Tsinghua University)	287
Transient Liquid Phase Bonding Using AgSn-Alloys for Stress Reduced Sensor Mounting	293
 Demonstration of Patternable All-Cu Compliant Interconnections with Enhanced Manufacturability in Chip-to-Substrate Applications	301
Development of Low-Temperature, Pressureless Copper-to-Copper Bonding by Microfluidic Electroless Interconnection Process	308
 Scaling Package Interconnects Below 20µm Pitch with Hybrid Bonding	314
 Micro-Silver Sinter Paste Developed for Pressure Sintering on Bare Cu Surfaces under Air or Inert Atmosphere	323

Session 8: Fan-Out Packaging-Applications and Architectures

Millimeter-Wave Antenna in Fan-Out Wafer Level Packaging for 60 GHz WLAN Application Zihao Chen (Institute of Microelectronics - A*STAR), Lim Teck Guan (Institute of Microelectronics - A*STAR), David Soon Wee Ho (Institute of Microelectronics - A*STAR), and Surya Bhattacharya (Institute of Microelectronics - A*STAR)	331
3D Heterogeneous Integration with Multiple Stacking Fan-Out Package Feng-Cheng Hsu (TSMC), Jackson Lin (TSMC), Shuo-Mao Chen (TSMC), Po-Yao Lin (TSMC), Jerry Fang (TSMC), Jin-Hua Wang (TSMC), and Shin-Puu Jeng (TSMC)	337
Study of Advanced Fan-Out Packages for Mobile Applications	343
An RDL-First Fan-out Wafer Level Package for Heterogeneous Integration Applications Yu-Min Lin (Industrial Technology Research Institute), Sheng-Tsai Wu (Industrial Technology Research Institute), Wen-Wei Shen (Industrial Technology Research Institute), Shin-Yi Huang (Industrial Technology Research Institute), Tzu-Ying Kuo (Industrial Technology Research Institute), Ang-Ying Lin (Industrial Technology Research Institute), Tao-Chih Chang (Industrial Technology Research Institute), Hsiang-Hung Chang (Industrial Technology Research Institute), Shu-Man Lee (Industrial Technology Research Institute), Shu-Man Lee (Industrial Technology Research Institute), Chia-Hsin Lee (Brewer Science Taiwan/Brewer Science Inc.), Jay Su (Brewer Science Taiwan/Brewer Science Inc.), Xiao Liu (Brewer Science Taiwan/Brewer Science Inc.), Qi Wu (Brewer Science Taiwan/Brewer Science Inc.), and Kuan-Neng Chen (National Chiao Tung University)	349

Cheng-Ta Ko (Unimicron Technology Corporation), Henry Yang (Unimicron Technology Corporation), John Lau (ASM Pacific Technology Ltd.), Ming Li (ASM Pacific Technology Ltd.), Margie Li (ASM Pacific Technology Ltd.), Curry Lin (Unimicron Technology Corporation), JW Lin (Unimicron Technology Corporation), Tony Chen (Jiangyin Changdian Advanced Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Din Yuang Yang (Huavei Technologies Co. Ltd.), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Xinang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), N. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), See Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology). Jeffery Lo (Hong Kong University of Science and Technology). Jeffery Lo (Hong Kong University of Science and Technology). 364 Fengman Liu (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Yu Sun (System Packaging	Chip-First Fan-Out Panel-Level Packaging for Heterogeneous Integration	355
 Technology Corporation), John Luu (ASM Pacific Technology Ltd.), Ming Li (ASM Pacific Technology Ltd.), Margie Li (ASM Pacific Technology Lud.), Curry Lin (Unimicron Technology Corporation), JW Lin (Unimicron Technology Corporation), Tony Chen (Jiangyin Changdian Advanced Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jihi-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ltd.), Kin Wae Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Meve Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mivee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mixee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Mixee Tan (Isangyin Changdian Advanced Packaging Co. Ltd.), Xin Cheung (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Mare Lin (Dow Chemical Company), YH Chen (Unimicrom Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Kao Suu Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technology Eo, Juli, Yiang Ku (Sience and Technology), Jeffery L (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology),	Cheng-Ta Ko (Unimicron Technology Corporation), Henry Yang (Unimicron	
Li (ASM Pacific Technology Ltd.), Margie Li (ASM Pacific Technology Ltd.), Curry Lin (Unimicron Technology Corporation), W Lin (Unimicron Technology Corporation), Tony Chen (Jiangyin Changdian Advanced Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ltd.), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Shee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Con Xi (Huawei Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology and Ricky Lee (Hong Kong University of Science and Technology and Ricky Lee (Hong Kong University of Science and Technology, and Ricky Lee (Hong Kong University o	Technology Corporation). John Lau (ASM Pacific Technology Ltd.). Ming	
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 Technology Corporation), Tony Chen (Jiangyin Changdian Advanced Packaging Co. Ld.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ld.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ld.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ld.), Nelson Fan (ASM Pacific Technology Ld.), Eric Kuah (ASM Pacific Technology Ld.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ld.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ld.), X. M. Cheung (ASM Pacific Technology Ld.), Eric Ng Ng (ASM Pacific Technology Ld.), Wu Kai (ASM Pacific Technology Ld.), Eric Ng Ng (ASM Pacific Technology Ld.), Wu Kai (ASM Pacific Technology Ld.), Wa Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ld.), Sce Pei Lim (Indium Corporation), Nor Lee (Indium Corporation), Miam Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology 2000 (System Packaging and Integration Research Center), Gian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Gian She (National Center), Center), Haiyun Xue (System Packaging and Integration Research Center), Gian She (National Center), Center), Haiyun Xue (System Packaging and Integration Research Center), Gian She (National Center), Center), Haiyun Xue (System Packaging and Integration Research Center), Mang Ang Packaging and Integration Research Center), Mang Ang Packaging and Integration Research Center), Mang Yue (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Mang Yue (System Packaging and Integration Research Center), Yue Y	Ltd.), Curry Lin (Unimicron Technology Corporation), JW Lin (Unimicron	
 Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ltd.), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Km Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), X. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology). Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology 2000 (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Aus (System Packaging and Integration Research Center), Huinin He (System Packaging and Integration Resear	Technology Corporation), Tony Chen (Jiangyin Changdian Advanced	
 Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ltd.), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology). Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging	
Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang Yong (Huawei Technologies Co. Ltd.), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zinang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Mato (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Janaga Cao (System Packaging and Integration Research Center), Cong Yu System Packaging and Integration Research Center), Anang Cao (System Packaging and Integration Research Center), Mang Cao (System Packaging and Integration Research Center), Mang Cao (System Packaging and Integration Research Center), Conpi Janaga Cao (System Packaging and Integration Research Center), Conpi Janaga Cao (System Packaging and Integra	Co. Ltd.), Chieh-Lin Chang (Dow Chemical Company), Jhih-Yuan Pan (Dow	
 Yong (Huawei Technologies Co. Ltd), Nelson Fan (ASM Pacific Technology Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Chemical Company), Hsing-Hui Wu (Dow Chemical Company), Qing Xiang	
 Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology). Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Mueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Janaya Yu (System Packaging and Integration Research Center), Janaya Yu (System Packaging and Integration Research Center), And Liqiang Cao (System Packaging and Integration Research Center), And Liqiang Cao (System Packaging and Integration Research Center), And Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Yong (Huawei Technologies Co. Ltd), Nelson Fan (ASM Pacific Technology	
Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.) Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Marchan Liu (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Wangi Zhang (System Packaging and Integration Research Center), Jaoyao Yu (System Packaging and Integration Research Center), Jaoyao Yu (System Packaging and Integration Research Center), Wangi Zhang (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Ltd.), Eric Kuah (ASM Pacific Technology Ltd.), Zhang Li (Jiangyin	
Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology). Jeffery Lo (Hong Kong University of Science and Technology). Jeffery Lo (Hong Kong University of Science and Technology). Jeffery Lo (Hong Kong University of Science and Technology). Suffery Lo (Hong Kong University of Science and Technology). Suffery and Ricky Lee (Hong Kong University of Science and Technology). Suffery and Ricky Lee (Hong Kong University of Science and Technology). Suffery and Ricky Lee (Hong Kong University of Science and Technology). Suffery and Ricky International Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin	
 Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Stee Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Quan She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Huiyun Xue (System Packaging and Integration Research Center), Huiyun Xue (System Packaging and Integration Research Center), Huiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Janayo Yu (System Packaging and Integration Research Center), Anaoyo Yu (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM Pacific	
 (ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.), Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Fengman Liu (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Technology Ltd.), Eric Ng Ng (ASM Pacific Technology Ltd.), Wu Kai	
 Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company), YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	(ASM Pacific Technology Ltd.), Ji Hao (ASM Pacific Technology Ltd.),	
 YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Integration of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology Design and Integration and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Rozalia Beica (Dow Chemical Company), Marc Lin (Dow Chemical Company),	
 Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	YH Chen (Unimicron Technology Corporation), Zhong Cheng (Huawei	
Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Technologies Co. Ltd.), Koh Sau Wee (Huawei Technologies Co. Ltd.),	
 Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Jiang Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies	
Corporation), Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Co. Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium	
 Technology), Jeffery Lo (Hong Kong University of Science and Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Corporation), Mian Tao (Hong Kong University of Science and	
 Technology), and Ricky Lee (Hong Kong University of Science and Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Technology), Jeffery Lo (Hong Kong University of Science and	
Technology) Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Technology), and Ricky Lee (Hong Kong University of Science and	
 Design and Fabrication of Feasible 3D Optoelectronics Integration Based on Embedded IC Fanout Technology	Technology)	
 364 Fengman Liu (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Design and Exprication of Feasible 3D Ontoelectronics Integration Based on Embedded IC Fanout	
 Fengman Liu (System Packaging and Integration Research Center), Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Technology	364
 Xueping Guo (System Packaging and Integration Research Center), Qian She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Fenoman Liu (System Packaging and Integration Research Center)	
 She (National Center for Advanced Packaging), Fengze Hou (System Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Xueping Guo (System Packaging and Integration Research Center), Oian	
 Packaging and Integration Research Center), Haiyun Xue (System Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	She (National Center for Advanced Packaging). Fengze Hou (System	
 Packaging and Integration Research Center), Yu Sun (System Packaging and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Packaging and Integration Research Center). Haivun Xue (System	
 and Integration Research Center), Huimin He (System Packaging and Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Packaging and Integration Research Center), Yu Sun (System Packaging	
 Integration Research Center), Zhaoyao Yu (System Packaging and Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	and Integration Research Center). Huimin He (System Packaging and	
 Integration Research Center), Wenqi Zhang (System Packaging and Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-μm Pitch	Integration Research Center). Zhaovao Yu (System Packaging and	
 Integration Research Center), and Liqiang Cao (System Packaging and Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-μm Pitch	Integration Research Center), Wengi Zhang (System Packaging and	
Integration Research Center) A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Integration Research Center), and Ligiang Cao (System Packaging and	
A Novel Fan-Out Concept for Ultra-High Chip-to-Chip Interconnect Density with 20-µm Pitch	Integration Research Center)	
Arnita Podpod (IMEC), John Slabbekoorn (IMEC), Alain Phommahaxay (IMEC), Fabrice Duval (IMEC), Abdellah Salahouelhadj (IMEC), Mario Gonzalez (IMEC), Kenneth Rebibis (IMEC), Andy Miller (IMEC), Gerald	A Novel Fan Out Concept for Ultra High Chip to Chip Interconnect Density with 20 um Pitch	270
(IMEC), Fabrice Duval (IMEC), Abdellah Salahouelhadj (IMEC), Mario Gonzalez (IMEC), Kenneth Rebibis (IMEC), Andy Miller (IMEC), Gerald	Arnita Podnod (IMFC) John Slabhekoorn (IMFC) Alain Phommaharay	
Gonzalez (IMEC), Kenneth Rebibis (IMEC), Andy Miller (IMEC), Gerald	(IMEC) Fabrice Duval (IMEC) Abdellah Salahouelhadi (IMEC) Mario	
	Gonzalez (IMEC) Kenneth Rebibis (IMEC) Andy Miller (IMEC) Gerald	

Beyer (IMEC), and Eric Beyne (IMEC)

Session 9: Flip Chip Manufacturing Challenges

Low-Temperature Assembly of Surface-Mount Device on Flexible Substrate Using Additive Printing	
Process	. 379
Christine Taylor (Georgia Institute of Technology), Xuanke He (Georgia	
Institute of Technology), Vanessa Smet (Georgia Institute of	
Technology), Manos Tentzeris (Georgia Institute of Technology), and	
Suresh Sitaraman (Georgia Institute of Technology)	

 Evaluation of Chip-Last Fan-Out Panel Level Packaging with G2.5 LCD Facility Using FlexUPTM and Mechanical De-bonding Technologies
Design and Application of Innovative Multi-table and Bond Head Drive System on Thermal Compression Bonder with UPH Over 2000
Adhesion Property of Polyimide and Passivation Layer for Polymer/metal Wafer-Level Hybrid Bonding in 3D Integration
 Advances in Memory Die Stacking
 Plasma Treatment for Fluxless Flip-Chip Chip-Joining Process
Effects of Laser Selective Reflow on Solder Joint Microstructure and Reliability

Session 10: Innovative Design, Modeling and Predictions for Reliability

Die Attach Delamination Analysis and Modeling Between Temperature Cycling and Thermal Shock for	
Exposed Pad Lead Frame Devices	434
Madison Koziol (Texas Instruments Inc.), Yutaka Suzuki (Texas	
Instruments Inc.), Siva Gurrum (Texas Instruments Inc.), and Muhammad	
Khan (Texas Instruments Inc.)	
A Comparison Study of Cu Dissolution Mechanism and Kinetics in Solder Joints under Electromigration	
and Extended Reflow	440
Deepak Goyal (Intel Corporation), Pilin Liu (Intel Corporation), and	
Alan Overson (Intel Corporation)	

Anand Parameters for Modeling Prolonged Storage on High Strain Rate Mechanical Properties of SAC-Q Leadfree Solder at High Operating Temperature <i>Pradeep Lall (Auburn University), Vikas Yadav (Auburn University),</i> <i>Jeff Suhling (Auburn University), and David Locker (US Army AMRDEC)</i>	. 448
Innovative Design of Crackstop Wall for 14nm Technology Node and Beyond Mohamed Rabie (GLOBALFOUNDRIES Inc.), Nicholas A. Polomoff (GLOBALFOUNDRIES Inc.), Md Khaled Hassan (GLOBALFOUNDRIES Inc.), Victoria L. Calero-DdelC (GLOBALFOUNDRIES Inc.), Danielle Degraw (GLOBALFOUNDRIES Inc.), Michael Hecker (GLOBALFOUNDRIES Inc.), Michael Thiele (GLOBALFOUNDRIES Inc.), and El Mehdi Bazizi (GLOBALFOUNDRIES Inc.)	. 460
Back-end-of-Line (BEOL) Mechanical Integrity Evaluation: A Mixed-Mode Double Cantilever Beam Test for Crackstop Strength Assessment	. 467
Study of the Long Term Reliability of 3D IC under Near-Application Conditions Omar Ahmed (University of Central Florida), Golareh Jalilvand (University of Central Florida), Jessica Dieguez (University of Central Florida), Peng Su (Juniper Networks), and Tengfei Jiang (University of Central Florida)	. 476
The Expermental and Numerical Study of Electromigration in 2.5D Packaging Jiefeng Xu (State University of New York at Binghamton), Yuling Niu (State University of New York at Binghamton), Stephen R. Cain (State University of New York at Binghamton), Scott McCann (Xilinx Inc.), Ho Hyung Lee (Xilinx Inc.), Gamal Refai-Ahmed (Xilinx Inc.), and S.B. Park (State University of New York at Binghamton)	. 483

Session 11: Emerging Packaging Technologies for 5G and Advanced Computing

Modeling and Design of a 3D Interconnect Based Circuit Cell Formed with 3D SiP Techniques Mimicking	
Brain Neurons for Neuromorphic Computing Applications	490
Min Miao (Beijing Information Science and Technology University),	
Liyuan Wang (Beijing Information Science and Technology University),	
Tianfang Chen (Beijing Information Science and Technology University),	
Lei Sun (Peking University), Xiaoyang Duan (Beijing Information	
Science and Technology), Jincan Zhang (Beijing Information Science and	
Technology University), Na Li (Beijing Information Science and	
Technology University), Runiu Fang (Peking University), Xin Sun	
(Peking University), Huan Liu (Peking University), and Yufeng Jin	
(Peking University)	
Surface Mount Electroosmotic Pump for Integrated Microfluidic Printed Circuit Boards	498
Sarkis Babikian (University of California). Makoto Jinsenii (OM Sangyo	
Co. Ltd.) Mark Bachman (Integra Daviers Inc.) and C.P. Li	
Co. Liu. J. Mark Dachman (Imegra Devices Inc.), and G.F. Li	

(University of California - Irvine)

Cryogenic Qubit Integration for Quantum Computing	504
Rabindra Das (MIT Lincoln Laboratory), Jonilyn Yoder (MIT Lincoln	
Laboratory), Danna Rosenberg (MIT Lincoln Laboratory), David Kim (MIT	
Lincoln Laboratory), Donna-Ruth Yost (MIT Lincoln Laboratory), Justin	
Mallek (MIT Lincoln Laboratory), David Hover (MIT Lincoln Laboratory),	
Vladimir Bolkhovsky (MIT Lincoln Laboratory), Andrew Kerman (MIT	
Lincoln Laboratory), and William Oliver (MIT Lincoln Laboratory)	
 A Novel Structure for Backside Protection Against Physical Attacks on Secure Chips or SiP Stephan Borel (CEA-Leti), L. Duperrex (CEA-Leti), E. Deschaseaux (CEA-Leti), J. Charbonnier (CEA-Leti), J. Cledière (CEA-Leti), R. Wacquez (CEA-Leti), J. Fournier (CEA-Leti), JC. Souriau (CEA-Leti), G. Simon (CEA-Leti), and A. Merle (CEA-Leti) 	515
Supply-Chain Security Enhancement by Chaotic Wireless Chip-Package-Board Interactive PUF	
Interconnect Technology Development for 180GHz Wireless mm-Wave System-in-Foil Transceivers Krzysztof Nieweglowski (Technische Universität Dresden), Patrick	527
Seiler (Technische Universität Dresden), David Fritsche (Technische	
Universität Dresden), Sebastian Lüngen (Technische Universität	
Dresden), Dirk Plettemeier (Technische Universität Dresden), Corrado	
Carta (Technische Universität Dresden), Frank Ellinger (Technische	
Universität Dresden), and Karlheinz Bock (Technische Universität	
Dresden)	
Long Range LiDAR Characterisation for Obstacle Detection for use by the Visually Impaired and Blind . Rosemary O'Keeffe (Tyndall National Institute). Salvatore Gnecchi	533
(SenL), Steve Buckley (SensL), Cian O'Murchu (Tyndall National	
Institute), Alan Mathewson (Tyndall National Institute), Suzanne	

Lesecq (CEA LETI), and Julie Foucault (C	CEA LETI)

Session 12: Sintering Pastes, Transient Liquid Phase and Direct Bonding

Pressure-Less Sintering on Large Dies Using Infrared Radiation and Optimized Silver Sinter Paste	. 539
Direct Bonding Silver to Aluminum Using Eutectic Reaction in Air Shao-Wei Fu (University of California - Irvine) and Chin C. Lee (University of California - Irvine)	. 545
Effects of the Interlayer Thickness and Alloying on the Reliability of Transient Liquid Phase (TLP) Bonding Junghyun Cho (Binghamton University - State University of New York), Fei Dong (Binghamton University - State University of New York), Liang Yin (GE Global Research), and David Shaddock (GE Global Research)	. 551
Nano-Cu Sintering Paste for High Power Devices Die Attach Applications Jinjin Zhao (Indium Corporation), Min Yao (Indium Corporation), and Ning-Cheng Lee (Indium Corporation)	. 557

Transient Liquid Phase Sintering Using Copper-Solder-Resin Composite for High-Temperature Power	
Modules	564
Hiroaki Tatsumi (Mitsubishi Electric Corporation), Adrian Lis (Osaka	
University), Takeshi Monodane (Mitsubishi Electric Corporation),	
Hiroshi Yamaguchi (Mitsubishi Electric Corporation), Yoshihiro Kashiba	
(Osaka University), and Akio Hirose (Osaka University)	
Detection of Liquefaction by DSC for Cu-Sn TLP Bonding Sylvain Lemettre (ULIS/C2N), Pierre Alphonse (CIRIMAT), Nathalie Isac (C2N), Sana Hammami (C2N), Seonho Seok (C2N), Johan Moulin (C2N), and Alain Bosseboeuf (C2N)	568
High Performance Metal-Based Nanocomposite Thermal Interface Materials Toward Enhanced Cooling Efficiency in Electronic Applications	574

Session 13: Fan-Out and Interposer Interconnections

 Chip Stackable, Ultra-thin, High-Flexibility 3D FOWLP (3D SWIFT® Technology) for Hetero-Integrated Advanced 3D WL-SiP	0
 High Performance, High Density RDL for Advanced Packaging	7
 Warpage Measurements and Characterizations of Fan-Out Wafer-Level Packaging with Large Chips and Multiple Redistributed Layers	4

Development of Novel Fine Line 2.1 D Package with Organic Interposer Using Advanced Substrate-Based Process	1
Micro Bump System for 2nd Generation Silicon Interposer with GPU and High Bandwidth Memory (HBM) Concurrent Integration	7
Low Cost Panel-Based 1-2 Micron RDL Technologies with Lower Resistance than Si BEOL for Large Packages	3
Advanced Anodic Aluminum Oxide Interposer Fabrication and 3D Embedded Inductors	9

Session 14: Advanced Substrates and Flip Chip Applications

2.5D Glass Panel Embedded (GPE) Packages with Better I/O Density, Performance, Cost and Reliability	(05
than Current Silicon Interposers and High-Density Fan-Out Packages	. 625
Siddharth Ravichandran (Georgia Institute of Technology), Shuhei	
Yamada (Murata Manufacturing Co. Ltd), Giback Park (Applied Materials	
Inc.), Han-Wen Chen (Applied Materials Inc.), Tailong Shi (Georgia	
Institute of Technology), Chintan Buch (Georgia Institute of	
Technology), Fuhan Liu (Georgia Institute of Technology), Vanessa Smet	
(Georgia Institute of Technology), Venky Sundaram (Georgia Institute	
of Technology), and Rao Tummala (Georgia Institute of Technology)	
Analysis of Warpage and Stress Behavior in a Fine Pitch Multi-Chip Interconnection with	
Ultrafine-Line Organic Substrate (2.1D)	631
Chen-Yu Huang (Siliconware Precision Industries Co. Ltd.), Yuan-Hung	
Hsu (Siliconware Precision Industries Co. Ltd.), Ying-Ju Lu	
(Siliconware Precision Industries Co. Ltd.), Kuo-Hua Yu (Siliconware	
Precision Industries Co. Ltd.), Wen-Shan Tsai (Siliconware Precision	
Industries Co. Ltd.), Chang-Fu Lin (Siliconware Precision Industries	
Co. Ltd.), and C. Key Chung (Siliconware Precision Industries Co.	
Ltd.)	

A Novel Application of Chemical Mechanical Polishing for Panel Level Organic and Glass Substrate Shyh-Lian Cheng (Unimicron Technology Corp.), Wei-Chun Chen (Unimicron Technology Corp.), Puru Bruce Lin (Unimicron Technology Corp.), Cheng-Ta Ko (Unimicron Technology Corp.), and Yu-Hua Chen (Unimicron Technology Corp.)	638
 Various Chip Attach Evaluations in a Fine Bump Pitch and Substrate Flip Chip Package ChiYuan Chen (MediaTek Inc.), Ian Hsu (MediaTek Inc.), Stanley Lin (MediaTek Inc.), KeonTaek Kang (STATS ChipPAC Pte. Ltd.), and Ming-Che Hsieh (STATS ChipPAC Pte. Ltd.) 	643
The Effect of the SnAg Solder Joint Morphology on the Thermal Cycle Reliability of 40 µm Fine-Pitch Cu-Pillar/SnAg Micro Bump Interconnection	649
Chip-Package Interaction Challenges for Large Die Applications	656
 Injection of Molten Solder (IMS) Technology for Solder Bumping on Wafers, Ceramic/Organic/Flexible Substrates, and Si Via Filling from Fine Pitch to Large Pitch	663

Session 15: Warpage Control in Assembly Processes

Reduce the Wafer Warpage Introduced by Cu in RDL Through Adjusting the Cooling Temperatures Gong Cheng (Chinese Academy of Sciences), Gaowei Xu (Chinese Academy of Sciences), Wei Gai (Chinese Academy of Sciences), and Le Luo (Chinese Academy of Sciences)	669
Ultra-Thin 50 um Fan-Out Wafer Level Package: Development of an Innovative Assembly and De-bonding	
Concept	675
Markus Woehrmann (Fraunhofer IZM), Tanja Braun (Fraunhofer IZM),	
Michael Toepper (Fraunhofer IZM), and Klaus-Dieter Land (Technische	
Universitaet Berlin)	
Design Guideline of 2.5D Package with Emphasis on Warpage Control and Thermal Management	682
Jisun Hong (Samsung Electronics), Kyoungsei Choi (Samsung	
Electronics), Dan Oh (Samsung Electronics), SB Park (The State	
University of New York at Binghamton), Shuai Shao (The State	
University of New York at Binghamton), Huayan Wang (The State	
University of New York at Binghamton), Yuling Niu (The State	
University of New York at Binghamton), and Van Lai Pham (The State	
University of New York at Binghamton)	

Stacking Yield Prediction of Package-on-Package Considering the Statistical Distributions of Top/Bottom Package Warpages and Solder Ball Heights <i>Hsiu-Ping Wei (University of Maryland) and Bongtae Han (University of Maryland)</i>	693
 Warpage Control During Mass Reflow Flip Chip Assembly Using Temporary Adhesive Bonding Normand-Pierre Goodhue (Université de Sherbrooke), David Danovitch (Université de Sherbrooke), Jeff Moussodji Moussodji (Université de Sherbrooke), Benoit Papineau (IBM Canada Ltd), and Eric Duchesne (IBM Canada Ltd) 	703
 Fabrication and Characterization of Epoxy Molding Films (EMFs) for Wafer-Level and Panel-Level Fan Out Packages JongHo Park (Korea Advanced Institute of Science and Technology), HanMin Lee (Korea Advanced Institute of Science and Technology), SeYoung Lee (Korea Advanced Institute of Science and Technology), Youjin Kyung (LG Chem R&D Center), Jung Hak Kim (LG Chem R&D Center), Kwangjoo Lee (LG Chem R&D Center), and Kyung-Wook Paik (Korea Advanced Institute of Science and Technology) 	712
Determination of a Meaningful Warpage Acceptance Criterion for Large PBGA Components Through the Correlation with Scattering in Material Properties <i>Qiming Zhang (The Hong Kong University of Science & Technology),</i> <i>Jeffery C. C. Lo (The Hong Kong University of Science & Technology),</i> <i>S. W. Ricky Lee (The Hong Kong University of Science & Technology),</i> <i>and Wei Xu (Huawei Technologies Co.)</i>	718

Session 16: Advances in Interconnect Reliability and Techniques

Reliability of Copper, Gold, Silver, and PCC Wirebonds Subjected to Harsh Environment	
 Study of Interface Micro-Voids Between Sputter Cu & Plating Cu: The Role of Photoresist	
 Prediction of Statistical Distribution of Vibration-Induced Solder Fatigue Failure Considering Intrinsic Variations of Mechanical Properties of Anisotropic Sn-Rich Solder Alloys	

 Experimental Strain Energy Density Dissipated in SAC305 Solder Joints During Different Thermal Cycling Conditions Using Strain Gages Measurements
Understanding the Impact of PCB Changes in the Latest Published JEDEC Board Level Drop Test Method 756 Varun Thukral (NXP Semiconductor), J.J.M. Zaal (NXP Semiconductor), R. Roucou (NXP Semiconductor), J. Jalink (NXP Semiconductor), and R.T.H Rongen (NXP Semiconductor)
 Non-destructive Inspection of Flip-Chip BGA Solder Ball Defects Using Two Laser Beam Probe Ultrasonic Inspection Technique
 Enhanced Design and Reliability Analysis of Copper Post Wafer Level Package

Session 17: Technology Advances in Nano, Biochemical, Thermal and Flexible Applications

Technology), Saswat Mishra (Georgia Institute of Technology), and Woon-Hong Yeo (Georgia Institute of Technology)

Cost-Efficient Formation of Flexible Pressure Sensor with Micropillar Arrays by Metal-Assisted Chemical Etching for Wearable Electronic Skin	790
A Harmonic RF Phase-Shifter Based Wireless pH Sensor Saikat Mondal (Michigan State University), Deepak Kumar (Michigan State University), Saranraj Karuppuswami (Michigan State University), and Premjeet Chahal (Michigan State University)	796
Integration of Chip-Scale SERF Atomic Magnetometers for Magnetoencephalography Measurement Guoliang Li (Southeast University), Jintang Shang (Southeast University), Yu Ji (Southeast University), Lin Lu (Southeast University), and Zhihua Pan (Southeast University)	802
Cu-In Fine-Pitch-Interconnects with Enhanced Shear Strength Steffen Bickel (Technische Universität Dresden), Robert Hoehne (Technische Universität Dresden), Iuliana Panchenko (Technische Universität Dresden), Joerg Meyer (Technische Universität Dresden), Iuliana Panchenko (Fraunhofer Institute for Reliability and Microintegration IZM), and M. Juergen Wolf (Fraunhofer Institute for Reliability and Microintegration IZM)	808
Study of Wearables with Embedded Electronics Through Experiments and Simulations Justin H. Chow (Georgia Institute of Technology), Suresh K. Sitaraman (Georgia Institute of Technology), Christopher May (Georgia Institute of Technology), and Joseph May (Georgia Institute of Technology)	814

Session 18: Silicon Photonics

Backside Optical I/O Module for Si Photonics Integrated with Electrical ICs Using Fan-Out Wafer	
Level Packaging Technology	822
Hiroshi Uemura (Photonics Electronics Technology Research	
Association), Kaori Warabi (Photonics Electronics Technology Research	
Association), Kazuya Ohira (Photonics Electronics Technology Research	
Association), Yoichiro Kurita (Photonics Electronics Technology	
Research Association), Haruhiko Yoshida (Photonics Electronics	
Technology Research Association), Hideto Furuyama (Photonics	
Electronics Lechnology Research Association), Yoshiaki Sugizaki	
(Tosniba Corporation), and Hideki Shibata (Tosniba Corporation)	
Single-Mode Optical Coupling Technology Using Movable Micro-Mirror Array and Surface-Emitting DFB	
Laser Array for High-Density 3-D Integration	828
Takanori Suzuki (Oclaro Janan) Koichiro Adachi (Oclaro Janan)	020
Variance is builded (Octains Suppling), Roteinio Function (Octains Suppling),	
Tasunobu Matsuoka (Octaro Japan), ana Shigenisa Tanaka (Octaro Japan)	
3D System-on-Packaging Using Through Silicon Via on SOI for High-Speed Optcal Interconnections with	with
Silicon Photonics Devices for Application of 400 Gbps and Beyond	834
Do-Won Kim (Institute of Microelectronics), Hong Yu Li (Institute of	
Microelectronics), Ka Fai Chang (Institute of Microelectronics), Woon	
Leng Loh (Institute of Microelectronics), Ser Choong Chong (Institute	
of Microelectronics), Hong Cai (Institute of Microelectronics), and	
Bhattacharya Surya (Institute of Microelectronics)	

Broadband, Polarization-Insensitive Lensed Edge Couplers for Silicon Photonics	
400 Gbps 2-Dimensional Optical Receiver Assembled on Wet Etched Silicon Interposer	;
EOCB-Platform for Integrated Photonic Chips Direct-on-Board Assembly within Tb/s Applications	ļ
 Integrated Multi-wavelength Laser Source for Sensing	,

Session 19: Interconnect Reliability

 Characterization of Material Damage and Microstructural Evolution Occurring in Lead Free Solders Subjected to Cyclic Loading	865
Effects of Au and Pd in Pad Surface Finish on Electro-Migration of Flip Chip Interconnection Between Cu-Pillar and Sn-Bi Solder Alloy System	875
The Stress State of BGA Solder Joints Influenced by the Grain Orientations of Neighboring Joints Andreas Lövberg (Swerea IVF AB) and Per-Erik Tegehall (Swerea IVF AB)	882
Microstructure Evolution of Cu/In/Cu Joints After Solid-Liquid Interdiffusion Yu Shan Chiu (National Taiwan University) and C. Robert Kao (National Taiwan University)	890

Isothermal Fatigue of Interconnections in Flexible Hybrid Electronics Based Human Performance Monitors
Rajesh Sharma Sivasubramony (Binghamton University), Nardeeka Adams (Binghamton University), Mohammed Alhendi (Binghamton University), Gurvinder Singh Khinda (Binghamton University), Maan Z Kokash (Binghamton University), Jack P Lombardi (Binghamton University), Arun Raj (Binghamton University), Sanoop Thekkut (Binghamton University), Darshana L Weerawarne (Binghamton University), Manu Yadav (Binghamton University), Ashwin Varkey Zachariah (Binghamton University), Nancy C Stoffel (GE Global Research), David M Shaddock (GE Global Research), Liang Yin (GE Global Research), Mark D Poliks (Binghamton University), and Peter Borgesen (Binghamton University)
Board Level Reliability Investigation of FO-WLP Package
 Multi-Axis Loading Impact on Thermo-Mechanical Stress-Induced Damage on WLCSP and Components With Via-in Pad Plated Over (VIPPO) Board Design Configuration

Session 20: MEMS, Sensor, IoT and Flex

 Development of a High Resolution Magnetic Field Position Sensor System Based on a Through Silicon Via First Integration Concept	916
 High Dielectric Constant Molding Compounds for Fingerprint Sensor Packages	.926
Concept for Using MID Technology for Advanced Packaging Ing. Wurz (Institute of Micro Production Technology), Marc Christopher Wurz (Institute of Micro Production Technology), Sebastian Bengsch (Institute of Micro Production Technology), Bernd Roesener (LPKF Laser & Electronics AG), and Sebastian Beringer (Institute of Micro Production Technology)	.932

Chipless RFID with Fully Inkjet Printed Tags: A Practical Case Study for Low Cost Smart Packaging Applications)
Low Temperature Solder Attach of SnAgCu Bumped Components for a Flexible Hybrid Electronics Based	
Medical Monitor	;
Thaer M. Alghoul (Binghamton University), Manu Yadav (Binghamton University), Sanoon Theklut (Pinghamton University), Paiesh S	
University), Sanoop Thekkui (Binghamion University), Kajesh S. Siyasubramony (Binghamton University), Christopher M. Greene	
(Ringhamton University) Mark D. Poliks (Ringhamton University) Peter	
Borgesen (Binghamton University), Luke Wentlent (Universal	
Instruments), Michael Meilunas (Universal Instruments), Nancy Stoffel	
(GE Global Research), David M. Shaddock (GE Global Research), and	
Liang Yin (GE Global Research)	
 Mechanical Strength Characterization of Direct Bond Interfaces for 3D-IC and MEMS Applications	ł
Study on an Improved Wafer Level Fabrication Process to Achieve Size Uniformity for Micro Glass	
Shell Resonators	2
Zhaoxi Su (Southeast University), Jintang Shang (Southeast University), Bin Luo (Southeast University), and Ching-Ping Wong (The Chinese University of Hong Kong)	

Session 21: Materials and Process Trends for Fan-Out Wafer Level Packaging

Warpage Control of Liquid Molding Compound for Fan-Out Wafer Level Packaging Yosuke Oi (Nagase ChemteX Corporation), Yasuhito Fujii (Nagase ChemteX Corporation), Takashi Hiraoka (Nagase ChemteX Corporation), Yukio Yada (Nagase ChemteX Corporation), and Katsushi Kan (Nagase ChemteX Corporation)	967
Warpage Analysis with Newly Molding Material of Fan-Out Panel Level Packaging and the Board Level	
Reliability Test Results	973
corporation), and Takashi Sugino (Lintec corporation)	
The Impact of Thermal Shrinkage of Glass Carriers on Achieving Fine Pitch Wiring Through Fan-Out	
WLP/PLP Process	. 979
Shuhei Nomura (AGC Asahi Glass) and Kazutaka Hayashi (AGC Asahi Glass)	

Advances in Temporary Bonding and Release Technology for Ultrathin Substrate Processing and High-Density Fan-Out Device Build-up Alain Phommahaxay (imec), Arnita Podpod (imec), John Slabbekoorn (imec), Erik Sleeckx (imec), Gerald Beyer (imec), Eric Beyne (imec), Alice Guerrero (Brewer Science), Dongshun Bai (Brewer Science), and Kim Arnold (Brewer Science)	985
Novel Microwave Process for RDL Photosensitive Dielectric Polymer Curing on FOWLP Reconstructed Wafer	.993
 Fabrication of Fine Via and Line / Space in Low CTE Film For Panel Fan-out Using a Dry Etching Technology	000
 Reliability Studies of Excimer Laser-Ablated Microvias Below 5 Micron Diameter in Dry Film Polymer Dielectrics for Next Generation, Panel-Scale 2.5D Interposer RDL	005

Session 22: Thermal Mechanical Modeling and Characterization

Seal Rings Toughness Characterization by Numerical and Experimental Approaches
 Reliability Life Assessment of WLCSP Using Different Creep Models
On the Uniqueness and Sensitivity of Nanoindentation Testing for Determining Elastic and Plastic Material Properties of Electroplating Copper Filled in Through-Silicon-Via (TSV)
Co-design for Extreme Large Package Solution with Embedded Fine Pitch Interposer (EFI) Technology 1030 Fa Xing Che (Institute of Microelectronics - A*STAR), David Ho (Institute of Microelectronics - A*STAR), and T.C. Chai (Institute of Microelectronics - A*STAR)

Study of Polyimide in Chip Package Interaction for Flip-Chip Cu-Pillar Packages
Wei Wang (Qualcomm Technologies Inc.), Dingyou Zhang (Qualcomm
Technologies Inc.), Yangyang Sun (Qualcomm Technologies Inc.), David
Rae (Qualcomm Technologies Inc.), Lily Zhao (Qualcomm Technologies
Inc.), Jiantao Zheng (Qualcomm Technologies Inc.), Mark Schwarz
(Qualcomm Technologies Inc.), Milind Shah (Qualcomm Technologies Inc.
), and Ahmer Syed (Qualcomm Technologies Inc.)
A Study of Organic Chip Carrier Fatigue Cracking
Developments for Highly Reliable Electronics - Experiments on Combined Thermal and Vibration Loading 1050
Meier Karsten (Technische Universität Dresden - Electronics Packging
Laboratory), Roellig Mike (Fraunhofer Institute for Ceramic
Technologies and Systems), and Bock Karlheinz (Technische Universität
Dresden - Electronics Packaging Laboratory)

Session 23: RF and THz Module Components

Package Co-design of a Fully Integrated Multimode 76-81GHz 45nm RFCMOS FMCW Automotive Radar Transceiver
Embedded Active Elements in 3D Printed Structures for the Design of RF Circuits
 Miniaturized High-Performance Filters for 5G Small-Cell Applications
3D-IPD with High Aspect Ratio Cu Pillar Inductor
Ultra-Compact, High-Performance, 3D-IPD Integrated Using Conformal 3D Interconnects

Glass in Electronic Packaging and Integration: High Q Inductances for 2.35 GHz Impedance Matching in	
0.05 mm Thin Glass Substrates	1089
Wu Zihan (PRC Georgia Tech), Sukhadha Viswanathan (PRC Georgia Tech),	
Matthias Jotz (SCHOTT AG), Holger Maune (TU Darmstadt), Matthias Jost	
(TU Darmstadt), P. Markondeya Raj (PRC Georgia Tech), Venkatesh	
Sundaram (PRC Georgia Tech), and Rao Tummala (PRC Georgia Tech)	
Through Glass Via (TGV) Based Band Pass Filter for 5G Communications	1097
Renuka Bowrothu (University of Florida), Yong-Kyu Yoon (University of	
Florida), and Jay Zhang (Corning Incorporated)	

Session 24: Optical Module Integration

Direct Fabrication for Polymer Optical Waveguide in PMT Ferrule Using the Mosquito Method 110 Takaaki Ishigure (Keio University), Hikaru Masuda (Keio University), Kumi Date (Keio University), Chinami Marushima (Keio University), and Tadayuki Enomoto (Keio University))3
Solder-Reflowable, High-Throughput Fiber Assembly Achieved by Partitioning of Adhesive Functions 110 Alexander Janta-Polczynski (IBM), Elaine Cyr (IBM), Richard Langlois (IBM), Paul Fortier (IBM), Yoichi Taira (IBM), Nicolas Boyer (IBM), and Tymon Barwicz (IBM))9
Low Reflectance and Reflowable Thermoplastic Optical Lens Without AR Coating	18
 Wide-Range 2D InP Chip-to-Fiber Alignment Through Bimorph Piezoelectric Actuators	24
Co-integration of High-Bandwidth Photonic and Electronic RDL on 2.5D Glass Interposers Using Low Optical Absorption Photoimageable Dielectric Polymer	30
 Thin Glass Based Optical Sub-Assemblies for Embedding in Electronic Systems	36

Session 25: Fabrication and Characterization of TSV

Low-Cost and Self-Formed Vertical Nanowires with Aspect Ratio >100x in Deep Si-Trenches for Future 3D-LSI/IC Applications
First Demonstration of Silicon-Like >250 I/O Per mm Per Layer Multilayer RDL on Glass Panel Interposers by Embedded Photo-Trench and Fly Cut Planarization
Dielectric Quality of 3D Capacitor Embedded in Through-Silicon Via (TSV)
Experimental Assessment and Analysis of the Influence of Radiation on Through-Silicon Vias
 Co-deposition of Nano-Size SiC Particles in Micro-Via
A Study of Crystal Orientation of Solder TSVs
Characterization of Optical End-Point Detection for Via Reveal Processing

Session 26: Wafer Level Packaging Fan-In and Fan-Out Key Developments

 Development of WLCSP for Accelerometer Packaging with Vertical CuPd Wire as Through Mold Interconnection (TMI)	188
 Fan Out Package: Performance and Scalability Perspective	.94
Board Level Reliability Enhancement of WLCSP with Large Chip Size	200
Controlling Underfill Lateral Flow to Improve Component Density in Heterogeneously Integrated Packaging Systems	206
Dual-Carrier Process Using Mechanical and Laser Release Technologies for Advanced Wafer-Level Packaging 12 Michelle Fowler (Brewer Science Inc.), John P. Massey (Brewer Science Inc.), Ramachandran K. Trichur (Brewer Science Inc.), and Matthew Koch (Brewer Science Inc.)	214
Optimization of Electrodeposited Copper for Sub 5 µm L/S Redistribution Layer Lines by Plating Additives	220
UBM/RDL Deposition by PVD for FOWLP in High Volume Production	226

Session 27: Automotive and Power Electronics

Embedded Components for High Temperature Automotive Applications	1233
Wolfgang Grübl (Continental), Stephanie Gross (Continental), and	
Bernhard Schuch (Continental)	

 New Failure Mechanism in High Temperature Resin Materials	38
Next Generation of Automotive Radar with Leading-Edge Advances in SiGe Devices and Glass Panel 124 Embedding (GPE) 124 Tailong Shi (Georgia Institute of Technology), Yunyi Gong (Georgia 124 Institute of Technology), Siddharth Ravichandran (Georgia Institute of 124 Technology), Venky Sundaram (Georgia Institute of Technology), John D. 126 Cressler (Georgia Institute of Technology), and Rao Tummala (Georgia 126 Institute of Technology) 126	45
 Solderless Leadframe Assisted Wafer-Level Packaging Technology for Power Electronics	51
 Material Characterization of Advanced Cement-Based Encapsulation Systems for Efficient Power Electronics with Increased Power Density	58
Mechanism of Ultrasonic-Assisted Sintering of Cu@Ag NPs Paste in air for High-Temperature Power Device Packaging	70
Design Consideration of a 3D Stacked Power Supply on Chip	76

Session 28: High-Speed and High-Bandwidth Packaging

Electrical Characterization of High Performance Fine Pitch Interconnects in Silicon-Interconnect	
Fabric	1283
SivaChandra Jangam (University of California - Los Angeles), Adeel	
Ahmed Bajwa (University of California - Los Angeles; Kulicke & Soffa	
Industries Inc.), Kannan K Thankkappan (University of California - Los	
Angeles), Premsagar Kittur (University of California - Los Angeles),	
and Subramanian Srikantes Iver (University of California - Los	
Angeles)	

 High Bandwidth Memory Interface on Organic Substrate: Challenges to Electrical Design
Advanced Fan-Out Package SI/PI/Thermal Performance Analysis of Novel RDL Packages
 FCBGA Fundamental Technology Realizing 56 Gbps PAM-4 System with 50 cm Electric Transmission 1302 Kazuyuki Nakagawa (Renesas Electronics Corporation), Norio Chujo (Hitachi Ltd.), Masayoshi Yagyu (Hitachi Ltd.), Yutaka Uematsu (Hitachi Ltd.), Keita Tsuchiya (Renesas Electronics Corporation), Shinji Katayama (Renesas Electronics Corporation), Yoshiaki Sato (Renesas Electronics Corporation), Hiroyuki Uchida (Renesas Electronics Corporation), and Shinji Baba (Renesas Electronics Corporation)
De-sensitization Design and Analysis for Highly Integrated RFSoC and DRAM Stacked-Die Design
Thermal Stability of Cu/Co Metaconductor and Its Millimeter Wave Applications1318Timothy Clingenpeel (University of Florida), Seahee Hwangbo(University of Florida), Nicolas Garraud (University of Florida),David Arnold (University of Florida), and Yong-Kyu Yoon (University of Florida)
Comparative Study on Electrical Performance of eWLB, M-Series and Fan-Out Chip Last

Session 29: Modeling of Power Electronics

330
342

Simulation for Enhancing Automotive Power Module DBC Reliability During Assembly Process
A Methodology to Integrate Thermo-Mechanical Reliability Predictions into Co-design of Flip-Chip-On-Lead Devices
Siva Gurrum (Texas Instruments Inc.), Manu Prakuzhy (Texas Instruments Inc.), Guangxu Li (Texas Instruments Inc.), Hung-Yun Lin (Texas Instruments Inc.), Saumya Gandhi (Texas Instruments Inc.), J. Carlos
Arroyo (Texas Instruments Inc.), Frank Mortan (Texas Instruments Inc.), and Amit Nangia (Texas Instruments Inc.)
High Power-Density 3D Integrated Power Supply Module Based on Panel-Level PCB Embedded Technology 1365
Fengze Hou (National Center for Advanced Packaging), Xueping Guo (National Center for Advanced Packaging), Qidong Wang (National Center for Advanced Packaging), Wenbo Wang (Delft University of Technology), Tingyu Lin (National Center for Advanced Packaging), Liqiang Cao (Institute of Microelectronics of Chinese Academy of Sciences), G. Q. Zhang (Delft University of Technology), and J. A. Ferreira (Delft University of Technology)
Mars 2020 Rover Laser Power Supply Thermomechanical Analysis
 Mechanical Modelling of High Power Lateral IGBT for LED Driver Applications

Session 30: Emerging Materials and Technologies

 On-chip Solid-State CMOS Compatible Micro-Supercapacitors	382
 Fabrication of High Capacitance Density Capacitor Using Spray Coated Ba0.6Sr0.4TiO3 Thin Films	389
 Structuring Methods of Polymers for low Cost Sensor Manufacturing	396

Solely Calcine Controlled Ferroelectricity and Resistivity of Barium Titanate Thin Films and Their Advanced Memory Applications
Electrochemical Analysis of Mechanically Flexible Magnesiumion Battery Electrodes in a Polymer Gel Perchlorate Electrolyte
Demonstration of Hermetic Sealing on Ultra-Thin, Wafer-Integrated Aluminum-Polymer Capacitors for High-Voltage and High-Temperature Applications
 Hydrothermal Exfoliation for Two-Dimension Boron Nitride Nanosheets

Session 31: Advanced Wirebond and Interconnect Technologies

Effects of Epoxy Molding Compound on Electrical Resistance Degradation of Pd-Coated Cu Wire Bonds in the 175 °C to 225 °C Range	1427
Molecular Dynamics Simulation of Microwelds Formation and Breakage During Ultrasonic Copper Wire Bonding	1434
Yangyang Long (Leibniz Universität Hannover), Bo He (Leibniz	
Universität Hannover Hanover), Weizhe Cui (Leibniz Universität	
Hannover Hanover), Xiaoying Zhuang (Leibniz Universität Hannover	
Hanover), and Jens Twiefel (Leibniz Universität Hannover Hanover)	
Investigation for Highly Reliable Free Air Ball Formation for Silver Bonding Wire	1440
(Ninnon Steel & Sumikin Technology) Ryo Oishi (Ninnon Micrometal	
Corporation), and Takashi Yamada (Nippon Micrometal Corporation)	
Corrosion Mechanisms of Cu Wire Bonding on Al Pads	1446
Wentao Qin (On Semiconductor), Harold Anderson (On Semiconductor), Tom	
Anderson (On Semiconductor), George Chang (On Semiconductor), and	
Denise Barrientos (On Semiconductor)	

Low Temperature Solder - A Breakthrough Technology for Surface Mounted Devices
 Advances in Wire Bonding Technology to Overcome Resonance Conditions
 3-D Antenna-in-Package Design with Metallic Coating Technique

Session 32: Heterogeneous Integration

 Void-Free Copper Pillar Hybrid Wafer Bonding Using a BCB Based Polymer Adhesive and Chemical Mechanical Polishing
 Heterogeneous Integration Challenges Within Wafer Level Fan-Out SiP for Wearables and IoT
 Embedded Silicon Fan-Out (eSiFO): A Promising Wafer Level Packaging Technology for Multi-chip and 3D System Integration

"Hole-in-One TSV", a New Via Last Concept for High Density 3D-SOC Interconnects
Extremely Flexible (1mm Bending Radius) Biocompatible Heterogeneous Fan-Out Wafer-Level Platform with the Lowest Reported Die-Shift (<6 µm) and Reliable Flexible Cu-Based Interconnects
 Heterogeneous Multi-die Stitching: Technology Demonstration and Design Considerations
 Heterogeneous Integration Technology Demonstrations for Future Healthcare, IoT, and AI Computing Solutions

Session 33: Next Generation Materials and Processes for Through Vias and 3D Interconnects

Extreme Thinning of Si Wafers for Via-Last and Multi-wafer Stacking Applications	. 1523
Anne Jourdain (imec), Joeri De Vos (imec), Nouredine Rassoul (imec),	
Houman Zahedmanesh (imec), Andy Miller (imec), Gerald Beyer (imec),	
Eric Beyne (imec), Edward Walsby (SPTS Technologies), Jash Patel (SPTS	
Technologies), Oliver Ansell (SPTS Technologies), Huma Ashraf (SPTS	
Technologies), Dave Thomas (SPTS Technologies), Shifang Li	
(KLA-Tencor), Timothy Chang (KLA-Tencor), Stephen Hiebert	
(KLA-Tencor), Moritz Stoerring (KLA-Tencor), and Andrew Cross	
(KLA-1encor)	
Development of a Polyimide/SiC-Whisker/Nano-Particles Composite with High Thermal Conductivity and	
Low Coefficient of Thermal Expansion as Dielectric Layer for Interposer Application	1531
Yunna Sun (Shanghai Jiao Tong University), Jiangho Luo (Shanghai Jiao	
Tong University) Zhuqaing Yang (Shanghai Jiao Tong University) Yan	
Wang (Shanghai Jiao Tong University), Cuifu Ding (Shanghai Jiao Tong	
wang (shanghai Jiao Tong University), Guiju Ding (shanghai Jiao Tong	
University), and Zhenqian Wang (Clemson University)	
An Advanced Photosensitive Dielectric Material for High-Density RDL with Ultra-Small Photo-Vias and	
Ultra-Fine Line/Space in 2.5D Interposers and Fan-Out Packages	1537
Daichi OKamoto (Taivo Ink Mfa, Co. Ltd.) Voko Shibasaki (Taivo Ink	1007
Ducin OKamolo (Taiyo Ink Mjg. Co. Lia.), Toko Smoasaki (Taiyo Ink $M_{1} = 0$	
Mfg. Co. Lta.), Daisuke Shibata (Taiyo Ink Mfg. Co. Lta.), Tadaniko	
Hanada (Taiyo Ink Mfg. Co. Ltd.), Fuhan Liu (Georgia Institute of	
Technology 3D Systems Packaging Research Center), Venky Sundaram	
(Georgia Institute of Technology 3D Systems Packaging Research	
Center), and Rao R Tummala (Georgia Institute of Technology 3D Systems	
Packaging Research Center)	

Highly Productive Solder Interconnect Formation by Bump Stabbing for 3D-TSV Die Stacking	543
 Reliability Studies of 5 µm Diameter Photo Vias with Daisy Chain Resistance Using Dry Film Photosensitive Dielectric Material	550
 Metal-Alloy Cu Surface Passivation Leads to High Quality Fine-Pitch Bump-Less Cu-Cu Bonding for 3D IC and Heterogeneous Integration Applications	555
Interconnection Process Using Laser and Hybrid Underfill for LED Array Module on PET Substrate	561

Session 34: Fan-Out Wafer Level Package Reliability

Reliability of Fan-Out Wafer-Level Packaging with Large Chips and Multiple Re-Distributed Layers
John Lau (ASM), Ming Li (ASM), Let Tung (ASM), Mulgie Li (ASM), ging
Aung Tong (Huawet Technologies Co. Lia.), Zhong Cheng (Huawet
Technologies Co. Ltd.), Tony Chen (Jiangyin Changalan Advancea
Packaging Co. Ltd.), Iris Xu (Jiangyin Changdian Advanced Packaging
Co. Ltd.), Nelson Fan (ASM), Eric Kuah (ASM), Zhang Li (Jiangyin
Changdian Advanced Packaging Co. Ltd.), Kim Hwee Tan (Jiangyin
Changdian Advanced Packaging Co. Ltd.), Y. M. Cheung (ASM), Eric Ng
(ASM), Penny Lo (ASM), Wu Kai (ASM), Ji Hao (ASM), Rozalia Beica (Dow
Chemical Company), Koh Sau Wee (Huawei Technologies Co. Ltd.), Jiang
Ran (Huawei Technologies Co. Ltd.), Cao Xi (Huawei Technologies Co.
Ltd.), Sze Pei Lim (Indium Corporation), NC Lee (Indium Corporation),
Cheng-Ta Ko (Unimicron Technology Corporation), Henry Yang (Unimicron
Technology Corporation), YH Chen (Unimicron Technology Corporation),
Mian Tao (Hong Kong University of Science and Technology), Jeffery Lo
(Hong Kong University of Science and Technology) and Ricky Lee (Hong
(In the second
Kong Oniversity of Science and Teenhoussy)
Passivation Materials for a Reliable Fine Pitch RDL
Moreau Stéphane (CEA), Nacima Allouti (CEA), Céline Ribière (CEA),
Jean Charbonnier (CEA), David Bouchu (CEA), Jean-Philippe Michel

(CEA), Nicolas Buffet (CEA), and Pascal Chausse (CEA)

Experimentally Minimizing the Gap Distance Between Extra Tall Packages and PCB Using the Digital	1
Van-Lai Pham (Binghamton University), Yuling Niu (Binghamton University), Jing Wang (Binghamton University), Huayang Wang (Binghamton University), Charandeep Singh (Binghamton University), Seungbae Park (Binghamton University), Cheng Zhong (Huawei Technologies Co. Ltd.), Sau Wee Koh (Huawei Technologies Co. Ltd.), Jifan Wang (Huawei Technologies Co. Ltd.), and Shuai Shao (Binghamton University)	
Reliability of Ultra-Thin Embedded Silicon Fan-Out (eSiFO) Package Directly Assembled on PCB for	
 Mobile Applications	
Interfacial Strength Characterization and Simulation of the Stacked Copper-Polymer Structures in	
 Fan-out Packages	
Effects of Underfill on Thermo-Mechanical Behavior of Fan-out Wafer Level Package Used in PoP: An Experimental Study by Advancements of Real-Time Moiré Interferometry	1
 Reliability Study of Large Fan-Out BGA Solution on FinFET Process	

Session 35: Multiphysics and Solder Joint Reliability

Numerical Multiphysics Model for Cu-Al Wire Bond Corrosion Subjected to Highly-Accelerated Stress	
Test	. 1622
Pradeep Lall (Auburn University), Yihua Luo (Auburn University), and	
Luu Nguyen (Texas Instruments)	

Smart Packaging - Microscopic Temperature and Moisture Sensors Embedded in a Flip-Chip Package 1633 Aurore Quelennec (Université de Sherbrooke), Yosri Ayadi (Université de Sherbrooke), Quentin Vandier (Université de Sherbrooke), Éric Duchesne (IBM Canada Ltd), Hélène Frémont (Université de Bordeaux), and Dominique Drouin (Université de Sherbrooke)
Improving Solder Joint Reliability for PoP Packages in Current Mobile Ecosystem
 Experimental Investigation of Temperature and Mean Stress Effects on High Cycle Fatigue Behavior of SnAgCu-Solder Alloy
Water Effects in Polymers Through Molecular Dynamics
Comprehensive Study on 2.5D Package Design for Board-Level Reliability in Thermal Cycling and Power Cycling
Comparative Study on Mechanical and Thermal Performance of eWLB, M-Series [™] and Fan-Out Chip Last Packages

Session 36: Power Delivery Solutions for Components and Systems

Analog Power Filtering: Modeling, Measuring & Analog PI	1677
Matthew S. Doyle Mr. (IBM), Layne A. Berge Mr. (IBM), and Kyle B.	
Schoneck Mr. (IBM)	
Improved Staggered Through Silicon Via Inductors for RF and Power Applications	1686
Xiao Sun (imec), Geert Van der Plas (imec), and Eric Beyne (imec)	

592
'00
'06
'14
'20
7 7 7

Session 37: Interactive Presentations 1

 Achieving of Intensified Conductive Interconnections for Flex-on-Flex by Using Metal Passivated Copper – Copper Thermocompression Bonding	. 1726
Reliability Test of Organic Substrate Processed by Newly Desmear Method "PhotodesmearTM" Shinichi Endo (Ushio Inc.), Tomoyuki Habu (Ushio Inc.), Yasushi Muto (Ushio Inc.), and Shintaro Yabu (Ushio America Inc.)	. 1732
 Highly-Conductive Stretchable Electrically Conductive Composites by Halogenation Treatment and Its Application in Stretchable Electronics Peng Zheng (Fudan University), Haoyue Zhuo (Fudan University), Yuxiao Zou (Fudan University), Wei Guo (Huazhong University of Science and Technology), Hao Wu (Huazhong University of Science and Technology), and Zhuo Li (Fudan University) 	. 1738

Electroplating Enhanced Silver Nanowire Networks for Transparent Heaters	1745
Low Transmission Loss Film Material for High-Speed High-Frequency Devices	751
 Wet-Spun Graphene Sheets as Flexible Heat Spreaders for Efficient Thermal Management	1756
Aging Characteristics of Green Mold Compound for Use in Encapsulation of Microelectronic Devices 1 Subramani Manoharan (University of Maryland), Chandradip Patel (Schlumberger Technology Corporation), Steven Dunford (Schlumberger Technology Corporation), Carlos Morillo (University of Maryland), and Patrick McCluskey (University of Maryland)	762
Effective Stress Relief Without Jeopardizing Reliability in Overmolded Packages with Stress Buffers 1 A. Mavinkurve (NXP Semiconductors), Jeroen Zaal (NXP Semiconductors), Yukai Liang (NXP Semiconductors), Sean Xu (NXP Semiconductors), Antoine Storez (NXP Semiconductors), Yuan Guo (NXP Semiconductors), Seng Teng (NXP Semiconductors), and Sheila Chopin (NXP Semiconductors)	1768
 High Temperature Mechanical Behavior of SAC and SAC+X Lead Free Solders	1775
Flexible Wearable Biometric Band and Smartphone Application for Prevention of Sudden Causes of Death1 Pradeep Lall (Auburn University), Hao Zhang (Auburn University), and Rahul Lall (Stanford University)	1784
Backward Compatible Connectors for Next Generation PCIe Electrical I/O	1792
PCB Pin Area Wire Modeling Based on Representative Layer 2D Misregistration	1799
 Compact Low Power Avionics for the Europa Lander Concept and Other Missions to Ocean Worlds	807

Optimization of Laser Release Process for Throughput Enhancement of Fan-Out Wafer-Level Packaging 1818 <i>Chia-Hsin Lee (Brewer Science; National Chiao Tung University), Jay Su</i> <i>(Brewer Science), Xiao Liu (Brewer Science), Qi Wu (Brewer Science),</i> <i>Jim-Wein Lin (Unimicron Technology Corp.), Puru Lin (Unimicron</i> <i>Technology Corp.), Cheng-Ta Ko (Unimicron Technology Corp.), Yu-Hua</i> <i>Chen (Unimicron Technology Corp.), Wen-Wei Shen (Industrial Technology</i> <i>Research Institute), Tzu-Ying Kou (Industrial Technology Research</i> <i>Institute), Shin-Yi Huang (Industrial Technology Research Institute),</i> <i>Yu-Min Lin (Industrial Technology Research Institute),</i> <i>Yu-Min Lin (Industrial Technology Research Institute), and Ang-Ying Lin</i> <i>(Industrial Technology Research Institute)</i>
Thermally Conductive Underfill and Its Viscoelastic Properties Using Hexagonal Boron Nitride Nanofiller S. A. Razgaleh (North Carolina A&T State University) and Shyam Aravamudhan (North Carolina A&T State University)
Self-Assembly Technologies for FlexTrate [™]
 High Performance EMI Shielding Materials and Spraying Process Parameters for High Frequency FCBGA Application
 Physical Aging of Epoxy Molding Compound and Its Influences on the Warpage of Reconstituted Wafer 1842 Tz-Cheng Chiu (National Cheng Kung University), Wei-Jie Yin (ASE Group Kaohsiung), En-Yu Yeh (National Cheng Kung University), Yu-Ting Yang (ASE Group Chung-Li), Dao-Long Chen (ASE Group Kaohsiung), and Yi-Hsiu Tseng (ASE Group Chung-Li)
 High Thermal Conductive Semi-Sintering Die Attach Paste
 Non-destructive Assessment of the Porosity in Silver (Ag) Sinter Joints Using Acoustic Waves

Reliability Study and Finite Element Modeling of a Wearable Sensor Patch (WSP) to Monitor ECG	
Signals	1865
Mark Poliks (Binghamton University), Varun Soman (Binghamton	
University), James Turner (Binghamton University), Mark Schadt (i3	
Electronics Inc.), Michael Shay (i3 Electronics Inc.), and Frank	
Egitto (i3 Electronics Inc.)	

Session 38: Interactive Presentations 2

Fabrication and Characteristics of Spin-on Dielectric for Multi-level Interconnect in WLP
High Density TSV-Free Interposer (TFI) Packaging with Submicron Cu Damascene RDLs for Integration of 1879 CPU/GPU and HBM 1879 Masaya Kawano (Institute of Microelectronics), Chum-Mei Wang 1879 (Institute of Microelectronics), Hong-Yu Li (Institute of 1879 Microelectronics), Mian-Zhi Ding (Institute of Microelectronics), Sharon Pei-Siang Lim (Institute of Microelectronics), Sharon Pei-Siang Lim (Institute of Microelectronics), Zi-Hao Chen (Institute of Microelectronics) Microelectronics), and Fa-Xing Che (Institute of Microelectronics) Microelectronics)
Dynamic Warpage Analysis of QFP Packages During Soldering Reflow Process and Thermal Cycle
Improvement of Mechanical Properties of Zn-Added Sn58Bi Alloy by Zn Segregation on the Sn-Bi Phase Boundaries During Thermal Aging
Low Dielectric Properties Encapsulation for High Frequency Devices
Controlling Die Warpage by Applying Under Bump Metallurgy for Fan-Out Package Process Applications 1906 Hwan-Pil Park (Hanyang University), Young-Ho Kim (Hanyang University), Young-Moon Jang (Seoul National University of Science and Technology), and Sung-Hoon Choa (Seoul National University of Science and Technology)
Influence of Metallization and Size on the Conductive Properties of Metal-Coated Polymer Particles in Anisotropic Conductive Adhesive
Demonstration of a Heterogeneously Integrated System-on-Wafer (SoW) Assembly

Novel Temporary Adhesive Materials for RDL-First Fan-Out Wafer-Level Packaging	
 The Reliability and the Effect of NCA Trapping in Thermo-Compression Flip-Chip Solder Joints Fabricated Using Sn-Ag Solder Capped 40 µm Pitch Cu Pillar Bumps and Low Temperature Curable Non-Conductive Adhesive (NCA)	
Performance of Fine and Ultra-Fine Lead-Free Powders for Solder Paste Applications	
Laser-Based Full Cut Dicing Evaluations for Thin Si Wafers)
Thermal Design and Characterization of High Power SiC Inverter with Low Profile and Enhanced Thermal Performance 1950 Gongyue Tang (Institute of Microelectronics - A*STAR), Tai Chong Chai (Institute of Microelectronics - A*STAR), and Xiaowu Zhang (Institute of Microelectronics - A*STAR))
 Challenges of Large Body FCBGA on Board Level Assembly and Reliability	ì
 Optimization of Via Bottom Cleaning for Bumpless Interconnects and Wafer-on-Wafer (WOW) Integration 1962 Y. S. Kim (Tokyo Institute of Technology), S. Kodama (Tokyo Institute of Technology), Y. Mizushima (Tokyo Institute of Technology), N. Araki (Tokyo Institute of Technology), C. Hsiao (Industrial Technology Research Institute), H. Chang (Industrial Technology Research Institute), C. Lin (Industrial Technology Research Institute), and T. Ohba (Industrial Technology Research Institute) 	
 Design, Fabrication and Characterization of TSV Interposer Integrated 3D Capacitor for SIP Applications	

High-Speed Precision Handling Technology of Micro-Chip for Fan-Out Wafer Level Packaging (FOWLP) Application	975
Qianwen Chen (IBM), Li-wen Hung (IBM), Evan Colgan (IBM), Bo Wen (IBM), Bing Dang (IBM), Russell Budd (IBM), Jae-woong Nah (IBM), and John Knickerbocker (IBM)	
 A Novel Inorganic Substrate by Three Dimensionally Stacked Glass Core Technology	€
 High Reliability Sintered Silver-Indium Bonding with Anti-Oxidation Property for High Temperature Applications	€987
RF Characterization, Analysis and Miniaturization Impact of RDL Interconnects) 94
 Integration of the SERF Magnetometer and the Mz Magnetometer Using Micro-Fabricated Alkali Vapor Cell)01
Integrated Copper Heat Spreaders in Glass Panel Embedded Packages with Near-Zero Thermal Interface 20 Resistance 20 Nithin Nedumthakady (Georgia Institute of Technology), Bartlet 20 DeProspo (Georgia Institute of Technology), P. Markondeya Raj (Georgia 20 Institute of Technology), Venky Sundaram Sundaram (Georgia Institute 6 of Technology), Rao Tummala (Georgia Institute of Technology), Kyle 8 Byers (Kansas City National Security Campus), Sean Garrison (Kansas 20 City National Security Campus), Chris Gibson (Sandia National Labs), and Michael Elsbury (Sandia National Labs) 20)07
Investigation of Material Dynamic Processes During Shear Test of Aluminum Heavy Wire Bond Contacts 20 Robert Klengel (Fraunhofer Institute for Microstructure of Materials and Systems IMWS), Falk Naumann (Fraunhofer Institute for Microstructure of Materials and Systems IMWS), Sebastian Tismer (Fraunhofer Institute for Microstructure of Materials and Systems IMWS), and Sandy Klengel (Fraunhofer Institute for Microstructure of Materials and Systems IMWS))13

Leading-Edge and Ultra-Thin 3D Glass-Polymer 5G Modules with Seamless Antenna-to-Transceiver Signal
Transmissions
Atom Watanabe (Georgia Institute of Technology), Tong-Hong Lin
(Georgia Institute of Technology), P. Markondeya Raj (Georgia
Institute of Technology), Venky Sundaram (Georgia Institute of
Technology), Manos M. Tentzeris (Georgia Institute of Technology), Rao
R. Tummala (Georgia Institute of Technology), and Tomonori Ogawa
(Asahi Glass Company)
Effect of Surface Finish and High Bi Solder Alloy on Component Reliability in Thermal Cycling
Electromigration Behavior and Mechanical Properties of the Whole Preferred Orientation Intermetallic Compound Interconnects for 3D Packaging

Session 39: Interactive Presentations 3

Comparison of Package-on-Package Technologies Utilizing Flip Chip and Fan-Out Wafer Level Packaging 2083 Amy Lujan (SavanSys Solutions LLC)
 Fork Type Structure of Silicon Waveguide for Optical Efficiency Optimization
Effect of Improved Optimization of DFE Equalization on Crosstalk and Jitter in High Speed Links with Multi-level Signal
Copper Transparent Antennas on Flexible Glass by Subtractive and Semi-Additive Fabrication for Automotive Applications
Correlated Model for Wafer Warpage Prediction of Arbitrarily Patterned Films
Thermomechanical Properties of Fan-Out Wafer Level Package with Various Chip and Mold Thickness 2115 Haksan Jeong (Sungkyunkwan University), Woo-Ram Myung (Sungkyunkwan University), Kwang-Ho Jung (Sungkyunkwan University), and Seung-Boo Jung (Sungkyunkwan University)
Design of a Compact Broadband Butler Matrix and Its Application in Organic Beam-Former at the 5 GHz Band
 Three-Dimensional Simulation of Effects of Microstructure Evolution and Interfacial Delamination on Cu Protrusion in Copper Filled Through Silicon Vias by Combined Monte Carlo and Finite Element Methods
Electrical Design for the Development of FOWLP for HBM Integration

Accurate Electrical Modeling of Through Silicon Via with Minority Carrier Redistribution Effect 2143 Huan Liu (Peking University), Runiu Fang (Peking University), Xin Sun (Peking University), Min Miao (Beijing Information Science and Technology University), and Yufeng Jin (Peking University Shenzhen Graduate School)
Thermal and Electrical Characterization of TSV Interposer Embedded with Microchannel for 2.5D 2150 Integration of GaN RF Devices 2150 Han Cai (Xiamen University), Shenglin Ma (Xiamen University), Wei Wang (Peking University), Yufeng Jin (Peking University), Jing Chen (Peking University), Jian Zhang (Southwest China Research Institute of Electronic Equipment), Weiwei Xiang (Southwest China Research Institute of Electronic), Liulin Hu (Chengdu Ganide Technology Co.), and Shuwei He (Chengdu Ganide Technology Co.)
Alternative Deposition Solution for Cost Reduction of TSV Integration
Evaluation of Mechanical Stress Induced During IC Packaging
 Wireless EAS Sensor Tags for Volatile Profiling in Food Packages
 High Throughput and Improved Edge Straightness for Memory Applications Using Stealth Dicing
Thick 3D Printed RF Components: Transmission Lines and Bandpass Filters
Introduction of a New Metric for the Solder Joint Reliability Assessment of BGA Packages on System Level
Compact Optical Coherent Receiver for Avionics Applications

Parylene as a Dielectric Material for Electronic Applications in Space	2199
Franz Selbmann (TU Bergakademie Freiberg & Fraunhofer ENAS Chemnitz),	
Mario Baum (TU Bergakademie Freiberg & Fraunhofer ENAS Chemnitz), Maik	
Wiemer (Fraunhofer ENAS Chemnitz), Yvonne Joseph (TU Bergakademie	
Freiberg), and Thomas Otto (TU Chemnitz & Fraunhofer ENAS Chemnitz)	

Session 40: Interactive Presentations 4

Practical Design Method to Reduce Crosstalk for Silicon Wafer Integrated Fan-Out Technology (SWIFT®) Packages HoJeong Lim (Amkor Technology Inc.), JeongKyu Yang (Amkor Technology Inc.), and Ruben Fuentes (Amkor Technology Inc.)
Fully Inkjet-Printed Three-Dimensional Bandpass Filter on Liquid Crystal Polymer Substrate
A Dynamic Bending Method for PoP Package Board Level Reliability Validation
Eliminating Harmful Intermetallic Compound Phase in Silver Wire Bonding by Alloying Silver with Indium
Cyanate Ester/Epoxy Co-Curing System with Thermal Stabilizers for High Temperature Stability
Demonstration of 28GHz Band Pass Filter Toward 5G Using Ultra Low Loss and High Accuracy Through Quartz Vias
 Micromesh-Enabled Low-Cost Thermal Ground Planes for High Heat Flux Power Electronics
3D Integration of Physics System Using Foldable Packaging for MEMS Atomic Clocks

Die Edge Crack Propagation Modeling for Risk Assessment of Advanced Technology Nodes
Development of a Through-Silicon Via (TSV) Process Module for Multi-project Wafer SiGe BiCMOS and Silicon Interposer
A New, Efficient Method for Preparation of 3D Integrated Systems by Laser Techniques
Effect of Interaction Between Multiple Defects on Z-Depth Estimate in Lock-in Thermography Applications
Practical High Speed PCB Stackup Tool - Generation and Validation
A Volatile Molecular Sensor Using Terahertz Resonators on Porous Substrates
Effects of the Adhesion Strength on the Bending Fatigue Behavior of Cu Pattern Laminated Fabrics Using B-Stage Non-Conductive Films (NCFs)
Process Development of 4-Die Stack Module Using Moldable Underfill
Integrated Fully Solid-State Capacitor Based on Carbon Nanofibers and Dielectrics
Effects of ACFs Modulus and Adhesion Strength on the Bending Reliability of CIF (Chip-in-Flex) Packages at Humid Environment 2313 Ji-Hye Kim (KAIST), Tae-Ik Lee (KAIST), Taek-Soo Kim (KAIST), and Kyung-Wook Paik (KAIST)

 Warpage Simulation/ Experiments and Analysis of 12" Wafer Level Fan-Out Packaging Technology
Design Considerations of a Matching Circuit for Low Power Wake-Up Receivers
Novel Solder Alloy with Wide Service Temperature Capability for Automotive Applications
Warpage and Reliability Challenges for Stacked Silicon Interconnect Technology in Large Packages
Effect of Shallow Cycling on Flexible Power-Source Survivability under Bending Loads and Operating Temperatures Representative of Stresses of Daily Motion
Nanomechanical Characterization of Intermetallic Compounds in Lead Free Solder Joints
 Fan-Out Wafer-Level Packaging for Heterogeneous Integration

Session 41: Student Interactive Presentation

Machine Learning Driven Advanced Packaging and Miniaturization of IoT for Wireless Power Transfer Solutions	8
Hakki Mert Torun (Georgia Tech), Colin Pardue (Georgia Tech), Mohamed L. F Belleradj (Georgia Tech), Anto K. Davis (Georgia Tech), and Madhavan Swaminathan (Georgia Tech)	
Application of Additive Manufacturing Technologies for Realization of Multilayer Microstrip Directional Filter 237 Jakub Sorocki (AGH University of Science and Technology), Ilona 237 Piekarz (AGH University of Science and Technology), Slawomir 37 Gruszczynski (AGH University of Science and Technology), Slawomir 37 Wincza (AGH University of Science and Technology), Slawomir 37 Papapolymerou (Michigan State University) 37	6
3D Printed Liquid Jet Impingement Cooler: Demonstration, Opportunities and Challenges	3
 Design and Surface Modification of PET Substrates Using UV/Ozone Treatment for Roll-to-Roll Processed Solar Photovoltaic (PV) Module Packaging	1
A Study on the High Frequency Performance of Solder ACFs Joints for Flex-on-Board Applications Using Coplanar Waveguide	8
Low-Temperature Cu-Cu Bonding by Anti-Oxidative Copper Nanoparticle Paste	L
Deep Understanding the role of Cu in RDL to Warpage by Exploring the Warpage Evolution with Microstructural Changes	0
A 56 Gbps I/O Interface Design with Exact Power Source Simulation: Total I/O Circuit Design with over 28 GHz from Driver to Receiver Device Models	6

Enhancements on Underfill Materials' Thermal Conductivity by Insulation Coating Layer Control of 2423 Conductive Particles 2423 Tae-Ryong Kim (Ntrium Incorporation), Kisu Joo (Ntrium Incorporation), 2423 Boo Taek Lim (National Nanofab Center), Sung-Soon Choi (Korea 2423 Electronics Technology Institute), Boung Ju Lee (National Nanofab 2423 Center), Euijoon Yoon (Seoul National University), Se Young Jeong (Ntrium Incorporation), and Myung Jin Yim (Intel Corporation)	5
 Fabrication of Fe-4.5wt.% Si Magnetic Cores for Power Electronic Converters by Selective Laser Melting	
Accurate Core Alignment for Polymer Optical Waveguide in the Mosquito Method for High-Efficient Coupling	8
Synthesis of a Graphene Carbon Nanotube Hybrid Film by Joule Self-Heating CVD for Thermal Applications 2444 Josef Hansson (Chalmers University of Technology), Majid Kabiri Samani 2444 (Chalmers University of Technology), Andreas Nylander (Chalmers 2444 University of Technology), Lilei Ye (SHT Smart High Tech AB), Nan Wang 2444 (Chalmers University of Technology), Lilei Ye (SHT Smart High Tech AB), Nan Wang 2444 (Chalmers University of Technology), Torbjörn Nilsson (Chalmers 2444 University of Technology), and Johan Liu (Chalmers University of Technology) 2444	4
Size and Shape Effect in the Determination of the Fracture Strength of Silicon Nitride in MEMS Structures at High Temperatures	1
A Study on the Curing Properties and Viscosities of Non-Conductive Films (NCFs) for Sn-Ag Solder Bump Flip Chip Assembly	3
Suspended Microstrip Low-Pass Filter Realized Using FDM Type 3D Printing with Conductive Copper-Based Filament	4

Modeling and Design of 2.5D Package with Mitigated Warpage and Enhanced Thermo-Mechanical Reliability	2471
Jing Wang (State University of New York at Binghamton), Yuling Niu (State University of New York at Binghamton), Seungbae Park (State University of New York at Binghamton), and Alexander Yatskov (Juniper Networks)	
Piezoelectric Ceramics and Flexible Printed Circuits (FPCs) Interconnection Using Anisotropic	
Conductive Films (ACFs) for Ultrasound Transducers Assembly	2478
Jae-Hyeong Park (Korea Advanced Institute of Science and Technology)	
and Kyung-Wook Paik (Korea Advanced Institute of Science and	
Technology)	
Design, Fabrication and Characterization of a Novel TSV Interposer Integrated Inductor for RF	
Applications	2486
Yunheng Sun (Peking University Shenzhen Graduate School), Han Cai	
(Xiamen University), Jiwei Li (Xiamen University), Shenglin Ma (Xiamen	
University), Yufeng Jin (Peking University Shenzhen Graduate School),	
Wei Wang (Peking University), Jing Chen (Peking University), Min Miao	
(Beijing Information Science and Technology University), Liulin Hu	
(Chengdu Ganide Technology Co.), and Shuwei He (Chengdu Ganide	
Technology Co.)	
A Novel Integration of Stereolithography and Inkjet Printing for Multichip Modules with High	
Frequency Packaging Applications	2492
Ryan Bahr (Georgia Institute of Technology), Bijan Teharani (Georgia	
Institute of Technology), Manos Tentzeris (Georgia Institute of	
Technology), and Kyle Byers (DOE's Kansas City National Security	
Campus)	

Author Index